

Author index for papers in Volume 29

Pages are numbered consecutively through the volume: 1-108, January; 109-216, March; 217-328, May; 329-440, July; 441-544, September; and 545-625, November.

- Abrams, M., A. Blusson, V. Carrere, T. Nguyen, and Y. Rabu**
177 *Image processing applications for geologic mapping*
- Akella, Ramakrishna**
392 see Gershwin, Stanley B.
- Applegate, S., J. Bartlett, A. Bohnhoff, A. Campbell, and J. Molloy**
459 *Implementation of the resistive ribbon technology in a printer and correcting typewriter*
- Atkinson, J. M., R. D. Granata, H. Leidheiser, Jr., and D. G. McBride**
27 *Cathodic delamination of methyl methacrylate-based dry film polymers on copper*
- Barojas, Jorge**
11 see Chan, Derek Y. C.
- Bartlett, J.**
459 see Applegate, S.
- Bates, R. J. S. and L. A. Sauer**
580 *Jitter accommodation in token-passing ring LANs*
- Beraud, J. P.**
132 see Ungerboeck, G.
- Beraud, Jean Paul**
140 *Signal processor chip implementation*
- Blusson, A.**
177 see Abrams, M.
- Bogy, D. B.**
316 see Bouchard, G.
- Bohnhoff, A., D. Croley, S. Dyer, T. Green, R. Maddox, and L. Struttman**
494 *System controls for a resistive ribbon printer*
- Bohnhoff, A.**
459 see Applegate, S.
- Borucki, L., H. H. Hansen, and K. Varahramyan**
263 *FEDSS—A 2D semiconductor fabrication process simulator*
- Bouchard, G., D. B. Bogy, and F. E. Talke**
316 *An experimental comparison of the head/disk interface dynamics in 5¼- and 8-inch disk drives*
- Brannon, K. W.**
229 see O'Brien, R. R.
- Brown, James A.**
37 *A development of APL2 syntax*
- Buturla, Edward M.**
277 see Cottrell, Peter E.
- Buturla, Edward M.**
302 see Farrell, Edward J.
- Byrnes, Robert G.**
289 see Laux, Steven E.
- Campbell, A.**
459 see Applegate, S.
- Carnevali, P., L. Coletti, and S. Patarnello**
569 *Image processing by simulated annealing*
- Carrere, V.**
177 see Abrams, M.
- Chan, Derek Y. C., Douglas Henderson, Jorge Barojas, and Andrew M. Homola**
11 *The stability of a colloidal suspension of coated magnetic particles in an aqueous solution*
- Chang, F.-Y. and L. F. Wagner**
252 *The generation of three-dimensional bipolar transistor models for circuit analysis*
- Chang, F.-Y.**
218 see Knepper, R. W.
- Chevillat, P. R.**
132 see Ungerboeck, G.
- Chieu, T. C. and O. Sahni**
509 *Ink temperatures in resistive ribbon thermal transfer printing*
- Choong, Yong F.**
392 see Gershwin, Stanley B.
- Chow, We-Min, Edward A. MacNair, and Charles H. Sauer**
330 *Analysis of manufacturing systems by the Research Queueing Package*
- Cobb, R. H.**
478 see DeFosse, S. F.
- Coletti, L.**
569 see Carnevali, P.
- Cook, R. K.**
242 see Gaur, S. P.

- Corongiu, G.** and J. H. Detrich
422 *Large-scale scientific application programs in chemistry and physics on an experimental parallel computer system*
- Corson, Phillip L.**
302 see Farrell, Edward J.
- Cottrell, Peter E.** and Edward M. Buturla
277 *VLSI wiring capacitance*
- Couturier, C.**
147 see Galand, C.
- Croley, D.**
494 see Bohnhoff, A.
- Crooks, Walter**
449 see Pennington, Keith S.
- DeFosse, S. F.,** G. T. Williams, D. A. Gostomski, Jr., and R. H. Cobb
478 *Development of a membrane switch-type full-travel tactile keyboard*
- Detrich, J. H.**
422 see Corongiu, G.
- Dove, D. B.**
519 see Shih, K. K.
- Dyer, S.**
494 see Bohnhoff, A.
- Engelke, H.,** J. Grotrian, C. Scheuing, A. Schmackpfeffer, W. Schwarz, B. Solf, and J. Tomann
343 *Integrated Manufacturing Modeling System*
- Farrell, Edward J.,** Steven E. Laux, Phillip L. Corson, and Edward M. Buturla
302 *Animation and 3D color display of multiple-variable data: Application to semiconductor design*
- Fellenstein, Craig,** Charles O. Green, Lucinda M. Palmer, Adrian Walker, and David J. Wyler
413 *A prototype manufacturing knowledge base in Syllog*
- Galand, C.,** C. Couturier, G. Platel, and R. Vermot-Gauchy
147 *Voice-excited predictive coder (VEPC) implementation on a high-performance signal processor*
- Gaur, S. P.,** P. A. Habitz, Y.-J. Park, R. K. Cook, Y.-S. Huang, and L. F. Wagner
242 *Two-dimensional device simulation program: 2DP*
- Gaur, S. P.**
218 see Knepper, R. W.
- Gershwin, Stanley B.,** Ramakrishna Akella, and Yong F. Choong
392 *Short-term production scheduling of an automated manufacturing facility*
- Gostomski, D. A., Jr.**
478 see DeFosse, S. F.
- Granata, R. D.**
27 see Atkinson, J. M.
- Green, Charles O.**
413 see Fellenstein, Craig
- Green, T.**
494 see Bohnhoff, A.
- Grotrian, J.**
343 see Engelke, H.
- Haas, Peter J.** and Gerald S. Shedler
194 *Regenerative simulation methods for local area computer networks*
- Habitz, P. A.**
242 see Gaur, S. P.
- Haines, C. L.**
356 *An algorithm for carrier routing in a flexible material-handling system*
- Hansen, H. H.**
263 see Borucki, L.
- Henderson, Douglas**
11 see Chan, Derek Y. C.
- Hollis, Ralph L.**
363 see Taylor, Russell H.
- Homola, Andrew M.**
11 see Chan, Derek Y. C.
- Hsieh, C. M.**
229 see O'Brien, R. R.
- Huang, Y.-S.**
242 see Gaur, S. P.
- Kaeser, H.-P.**
132 see Ungerboeck, G.
- Knepper, R. W.,** S. P. Gaur, F.-Y. Chang, and G. R. Srinivasan
218 *Advanced bipolar transistor modeling: Process and device simulation tools for today's technology*
- Knepper, R. W.**
229 see O'Brien, R. R.
- Kotkiewicz, S. M.**
18 see Marsh, L. L.
- Laff, Robert A.** and Claus D. Makowka
527 *Thermal behavior of resistive ribbon for single-stylus excitation*
- Langdon, Glen G., Jr.**
188 see Todd, Stephen
- Langlois, W. E.**
2 *The dynamical equations governing a lubricating film consisting of a gas film overlying a liquid film*
- Laux, Steven E.** and Robert G. Byrnes
289 *Semiconductor device simulation using generalized mobility models*
- Laux, Steven E.**
302 see Farrell, Edward J.
- Lavin, Mark A.**
363 see Taylor, Russell H.
- Leidheiser, H., Jr.**
27 see Atkinson, J. M.
- Lever, R. F.**
229 see O'Brien, R. R.
- MacNair, Edward A.**
330 see Chow, We-Min
- Maddox, R.**
494 see Bohnhoff, A.
- Maiwald, D.**
132 see Ungerboeck, G.
- Makowka, Claus D.**
527 see Laff, Robert A.
- Mandeville, Jon R.**
73 *Novel method for analysis of printed circuit images*
- Marsh, L. L.,** D. C. Van Hart, and S. M. Kotkiewicz
18 *A dielectric loss investigation of moisture in epoxy-glass composites*
- Matino, Haruhiro**
588 *Analysis of the holding current in CMOS latch-up*
- Mayo, R. D.**
488 *System control for a printwheel typewriter*

- McBride, D. G.**
27 see Atkinson, J. M.
- Molloy, J.**
459 see Applegate, S.
- Moore, J. S.**
229 see O'Brien, R. R.
- Murley, P. C.**
229 see O'Brien, R. R.
- Nguyen, T.**
177 see Abrams, M.
- O'Brien, R. R., C. M. Hsieh, J. S. Moore, R. F. Lever, P. C. Murley, K. W. Brannon, G. R. Srinivasan, and R. W. Knepper**
229 *Two-dimensional process modeling: A description of the SAFEPRO program*
- O'Malley, Lawrence V.**
68 *Adaptive clustering algorithm*
- Palmer, Lucinda M.**
413 see Fellenstein, Craig
- Park, Y.-J.**
242 see Gaur, S. P.
- Patarnello, S.**
569 see Carnevali, P.
- Patel, Arvind M.**
546 *Adaptive cross-parity (AXP) code for a high-density magnetic tape subsystem*
- Pennington, Keith S. and Walter Crooks**
449 *Resistive ribbon thermal transfer printing: A historical review and introduction to a new printing technology*
- Platel, G.**
147 see Galand, C.
- Rabu, Y.**
177 see Abrams, M.
- Rayfield, James T. and Harvey F. Silverman**
170 *An approach to DFT calculations using standard microprocessors*
- Rissanen, Jorma**
188 see Todd, Stephen
- Sahni, O.**
509 see Chieu, T. C.
- Sauer, Charles H.**
330 see Chow, We-Min
- Sauer, L. A.**
580 see Bates, R. J. S.
- Scheuing, C.**
343 see Engelke, H.
- Schmackpfeffer, A.**
343 see Engelke, H.
- Schneider, Richard C.**
563 *Write equalization in high-linear-density magnetic recording*
- Schwarz, B.**
343 see Engelke, H.
- Shedler, Gerald S.**
194 see Haas, Peter J.
- Schichman, G.**
158 *Personal Instrument (PI)—A PC-based signal processing system*
- Shih, K. K. and D. B. Dove**
519 *Electrical properties of resistive ribbon*
- Silverman, Harvey F.**
170 see Rayfield, James T.
- Solf, B.**
343 see Engelke, H.
- Srinivasan, G. R.**
218 see Knepper, R. W.
- Srinivasan, G. R.**
229 see O'Brien, R. R.
- Stanley, Robert C.**
110 *Microprocessors in brief*
- Stapper, C. H.**
87 *The effects of wafer to wafer defect density variations on integrated circuit defect and fault distributions*
- Struttman, L.**
494 see Bohnhoff, A.
- Takagi, N. and C. K. Wong**
49 *A hardware sort-merge system*
- Talke, F. E.**
316 see Bouchard, G.
- Taylor, Russell H., Ralph L. Hollis, and Mark A. Lavin**
363 *Precise manipulation with endpoint sensing*
- Todd, Stephen, Glen G. Langdon, Jr., and Jorma Rissanen**
188 *Parameter reduction and context selection for compression of gray-scale images*
- Tomann, J.**
343 see Engelke, H.
- Twardeck, T. G.**
470 *Characterization of a resistive ribbon thermal transfer printing process*
- Ungerboeck, G., D. Maiwald, H.-P. Kaeser, P. R. Chevillat, and J. P. Beraud**
132 *Architecture of a digital signal processor*
- Van Hart, D. C.**
18 see Marsh, L. L.
- Varahramyan, K.**
263 see Borucki, L.
- Vermot-Gauchy, R.**
147 see Galand, C.
- Wagner, L. F.**
252 see Chang, F.-Y.
- Wagner, L. F.**
242 see Gaur, S. P.
- Walker, Adrian**
413 see Fellenstein, Craig
- Williams, G. T.**
478 see DeFosse, S. F.
- Williams, T. H.**
443 *Design and implementation of the *SELECTRIC System/2000*
- Wittrock, Robert J.**
401 *Scheduling algorithms for flexible flow lines*
- Wong, C. K.**
49 see Takagi, N.
- Wyler, David J.**
413 see Fellenstein, Craig
- Yashchin, Emmanuel**
377 *On the analysis and design of CUSUM-Shewhart control schemes*